

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	AMG/17/10392	
1.3 Title of PCN	New set of material in Amkor Philippines for TSSOP14 and TSSOP16 packages	
1.4 Product Category	Selected products in TSSOP14/16	
1.5 Issue date	2017-08-23	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Lorenzo NASO
2.1.2 Marketing Manager	Marcello SAN BIAGIO,Emanuele VAVASSORI
2.1.3 Quality Manager	Paolo MORETTI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Any change on substrate (part number, supplier, plant, design or composition of any layer?)	Amkor (ATP1) Philippines

4. Description of change

	Old	New
4.1 Description	Molding compound = SUMITOMO EME-G700K Lead-frame = Original Matrix Lead-Frame (OMLF)	Molding compound = Sumitomo G700LS Lead-frame = High Density Lead-Frame (HDLF) or eXtreme Density Lead-Frame (XDLF)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change

5.1 Motivation	Progressing on the activities related to quality continuous improvement, ST is glad to announce a new material set (molding compound) for TSSOP14 and TSSOP16 packages produced in Amkor Philippines. Besides, we will introduce a new lead-frame (XDLF) with higher density in order to increase our production capacity and rationalize our production tool. This change implies the phase out of the Old Lead Frame Matrix (OMLF) and High Density Lead Frame (HDLF), and it has no impact on the internal lead-frame structure.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	New finished-good codes
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7. Timing / schedule

7.1 Date of qualification results	2017-06-19
7.2 Intended start of delivery	2017-10-12
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	10392 Qual Report_TSSOP14-16- f.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2017-08-23
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9. Attachments (additional documentations)
10392 Public product.pdf 10392 Qual Report_TSSOP14-16- f.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
LM224PT	LM224PT	
LM239PT	LM239PT	
LM2901PT	LM2901PT	
LM2902PT	LM2902PT	
LM324PT	LM324PT	
LM339PT	LM339PT	
	PM8800A	
	PM8800ATR	
TS924AIPT	TS924AIPT	
TS934IPT	TS934IPT	
TS944IPT	TS944IPT	
	TSH345IPT	
TSH73CPT	TSH73CPT	
	TSU104IPT	
	TSV524AIPT	
	TSV524IPT	
	TSV714IPT	
	TSV734IPT	
	TSV994AIPT	
	TSV994IPT	
	TSZ124IPT	

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